

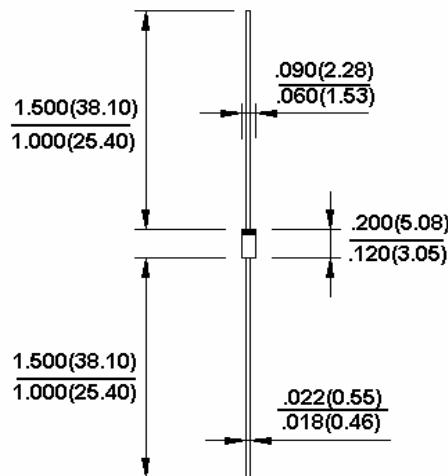


DO-35



### Features

- ❖ Fast switching device ( $T_{RR} < 4.0\text{nS}$ )
- ❖ DO-35 package (JEDEC)
- ❖ Through-hole device type mounting
- ❖ Hermetically sealed glass
- ❖ Compression bonded construction
- ❖ All external surface are corrosion resistant and leads are readily solderable
- ❖ RoHS compliant
- ❖ Solder hot dip Tin(Sn) lead finish
- ❖ Cathode indicated by polarity band



Dimensions in inches and(millimeters)

### Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

#### Maximum Ratings

Type Number	Symbol	Value	Units
Power Dissipation	Pd	500	mW
Working Inverse Voltage	WIV	75	V
Non-repetitive Peak Forward Current	IFM	450	mA
Average Rectified Current	Io	150	mA
Peak Forward Surge Current	I <sub>SURGE</sub>	2	A
Operating Junction Temperature	T <sub>J</sub>	175	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to + 200	°C

#### Electrical Characteristics

Type Number	Symbol	Min	Max	Units
Breakdown Voltage IR=100uA IR=5uA	B <sub>V</sub>	100 75		V
Forward Voltage 1N4448, 1N914B 1N4148 1N4448, 1N914B	V <sub>F</sub>	0.62	0.72 1.0 1.0	V
Reverse Leakage Current VR=20V VR=75V	I <sub>R</sub>		25 5	nA uA
Junction Capacitance VR=0, f=1.0MHz	C <sub>j</sub>	—	4.0	pF
Reverse Recovery Time (Note 1)	trr	—	4.0	nS

Notes: 1. Reverse Recovery Test Conditions: I<sub>F</sub>=10mA, VR=6V, R<sub>L</sub>=100Ω, I<sub>RR</sub>=1mA



### RATINGS AND CHARACTERISTIC CURVES (1N4448/1N4148/1N914B)

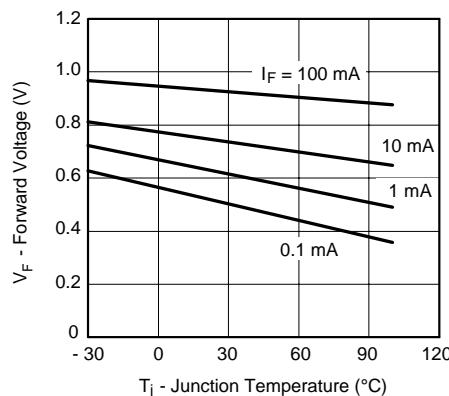


Figure 1. Forward Voltage vs. Junction Temperature

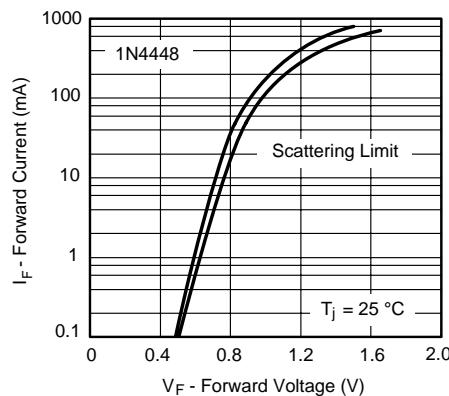


Figure 3. Forward Current vs. Forward Voltage

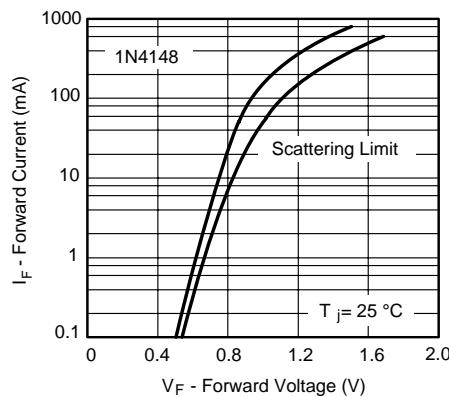


Figure 2. Forward Current vs. Forward Voltage

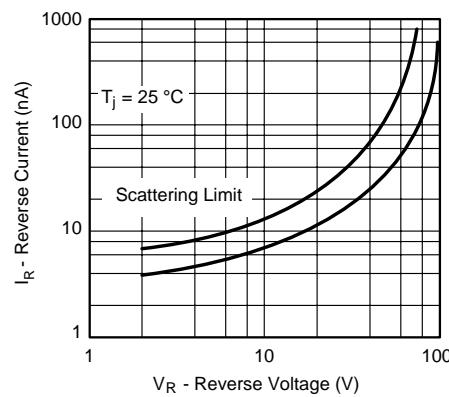


Figure 4. Reverse Current vs. Reverse Voltage

PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-35	5000/AMMO	100000	41X28.5X38	14.57	13.07